Docket No. 259/011

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DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

METHOD FOR CLE SEMICONDUCTOR DEV	IANING DAMAGE ICE	LAYER	AND	POLYMER	RESIDUE	FRC
ne specification of which is attached		x is checked:				
was filed ona	nd was amended on				ternational Applic	ation Nun
hereby state that I have reviewed nendment referred to above.					the claims, as ame	ended by
acknowledge the duty to disclose egulations § 1.56.	information which is known	by me to be ma	aterial to par	tentability as define	d in Title 37, Co	de of Fed
hereby claim foreign priority beneventor's certificate, or § 365(a) of a d have also identified below any for at of the application on which prior	ny PCT International application or ign application for patent or ity is claimed:	n which designate	ted at least o	ne country other that	n the United States	s, listed b
NUMBER	<u> </u>	COUNTRY		AY/MONTH/YEAR	- 1	ORITY IMED
				AT THE REPORT OF THE RESIDENCE OF THE RE		
ereby claim the benefit under Title	35, United States Code § 119(e) of any United	States provis	sional application(s)	listed below.	
APPLICATION NO.			FILING DATE			

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is known by me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application:

APPLICATION SERIAL NO.	FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

I hereby appoint as my attorneys, with full powers of substitution and revocation, to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: Eugene M. Lee, Reg. No. 32,039; Richard A. Sterba, Reg. No. 43,162.

Address all correspondence to Eugene M. Lee, The Law Offices of Eugene M. Lee, PLLC, 2111 Wilson Boulevard, Suite 1200, Arlington, Virginia 22201. Address all telephone communications to Eugene M. Lee at (703) 525-0978.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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